



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
9	15.Feb.2005	056722	ADDED LOT NUMBER RE-DRAW		K.INOUE		O.Hashiguchi

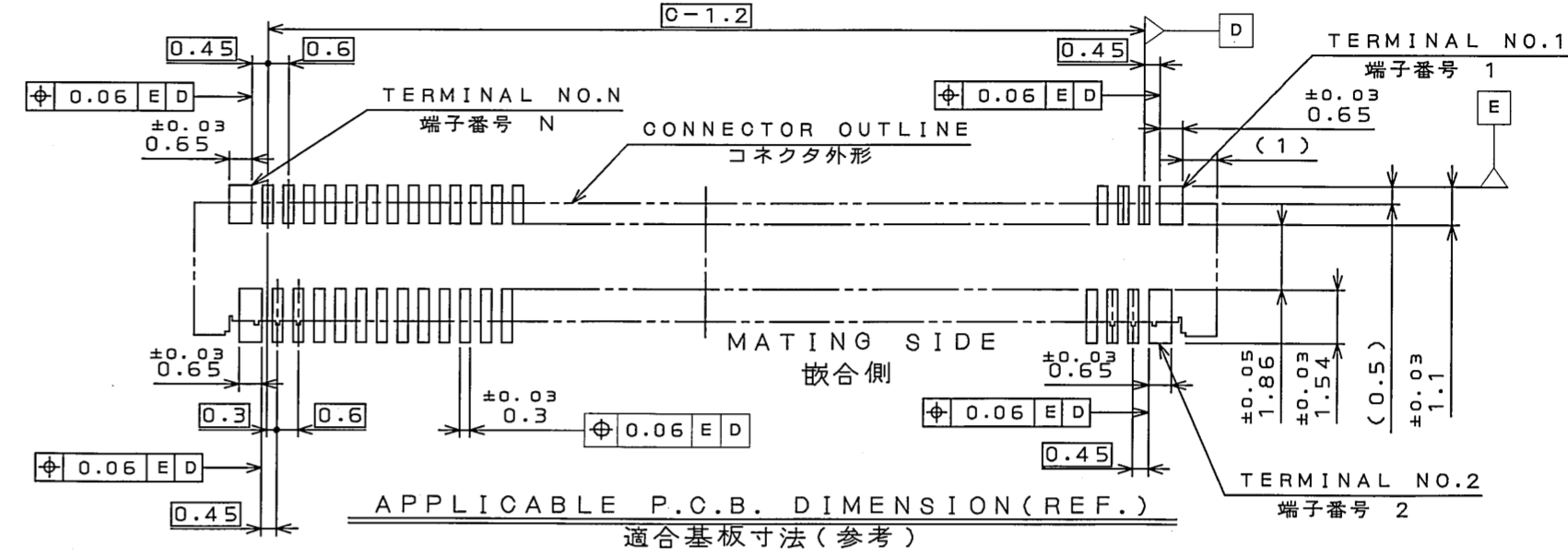
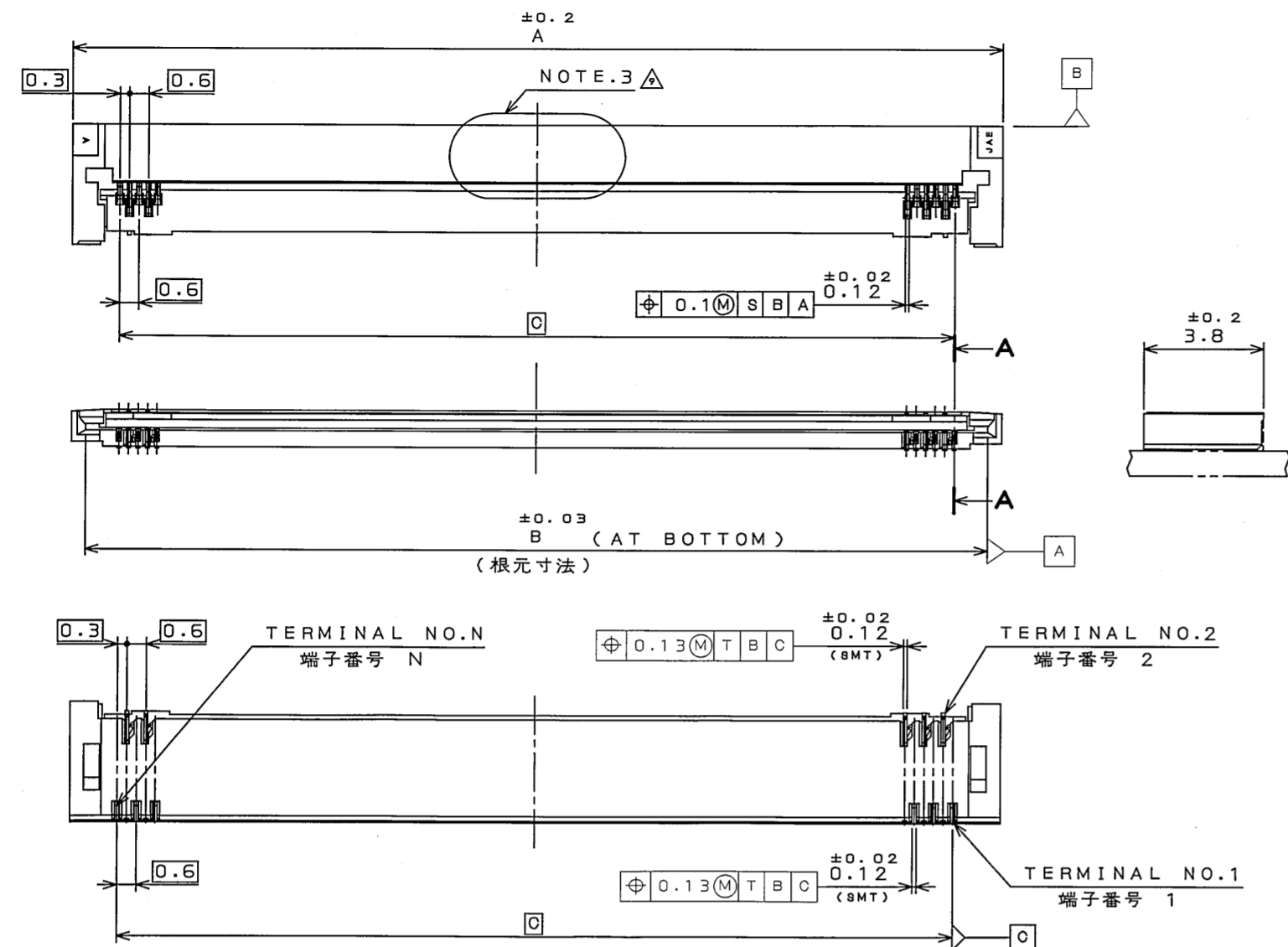
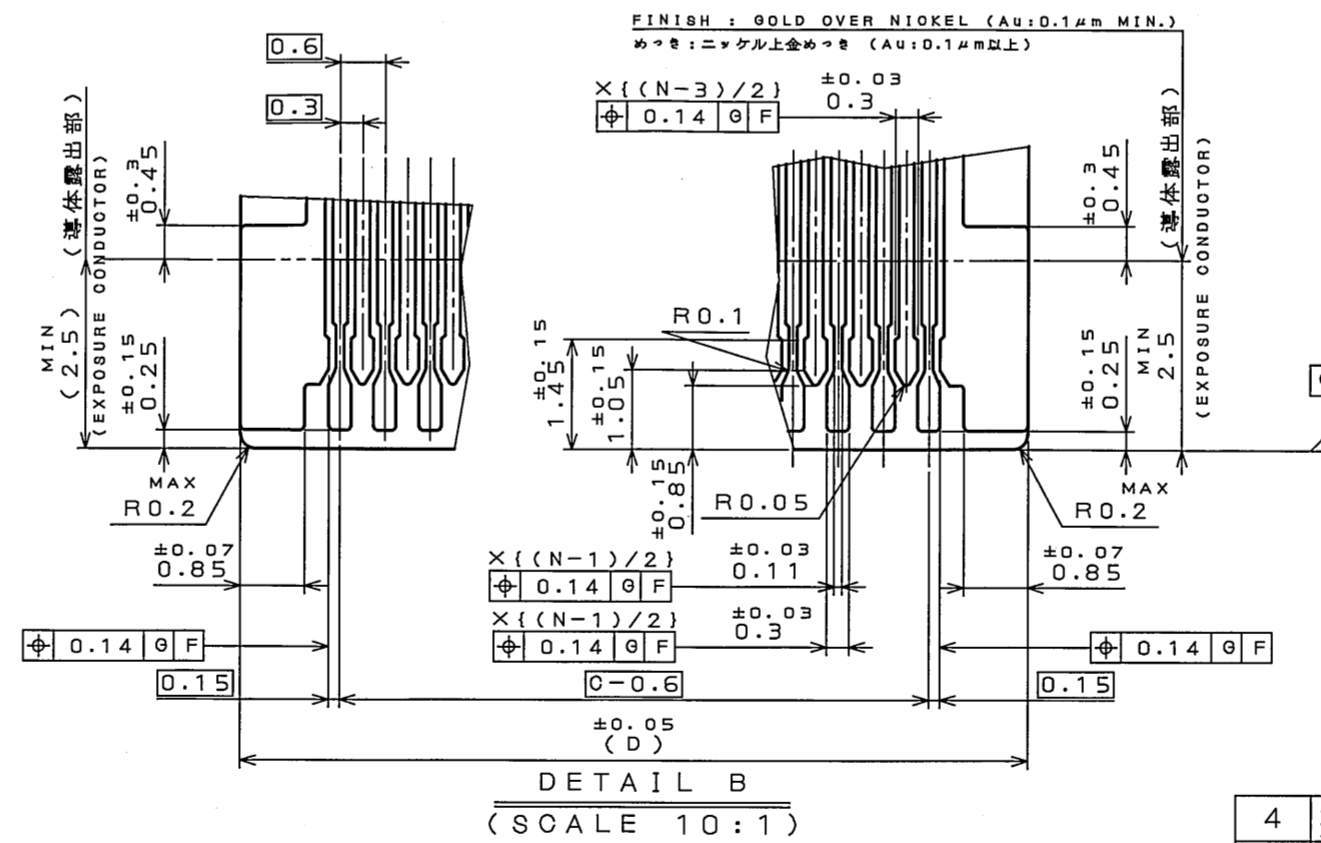
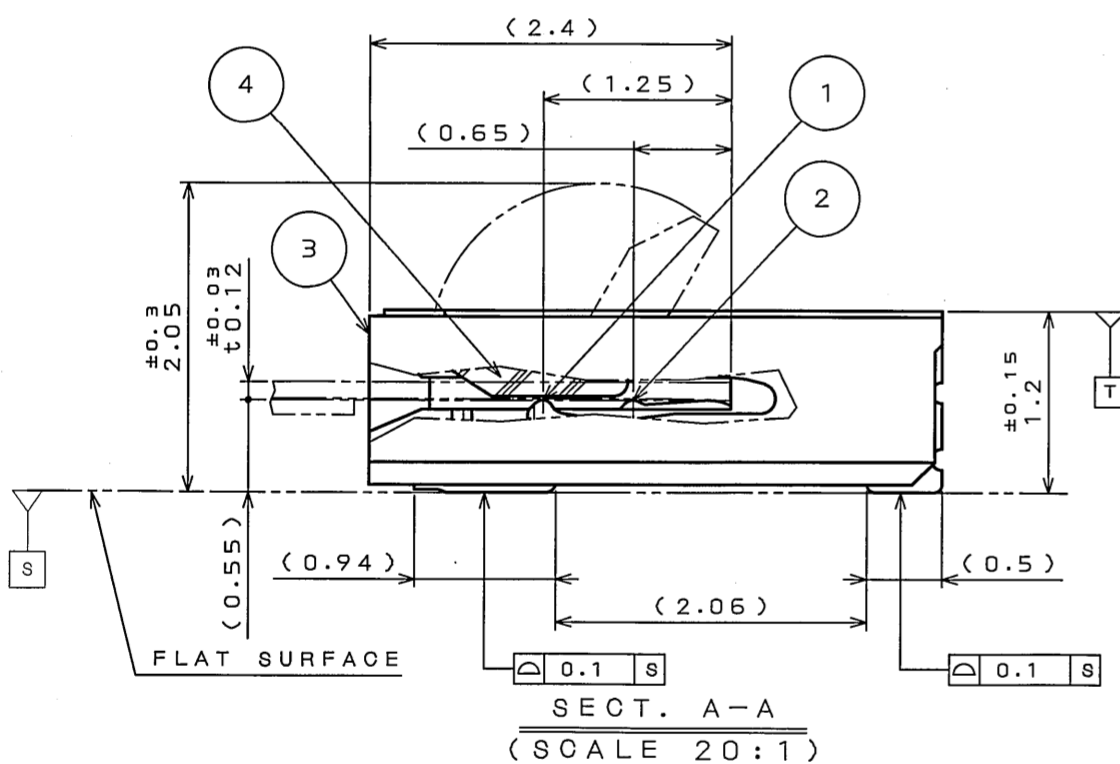


TABLE 1

PRODUCT NO. 品名	A	B	C	D
FF0255881	19.2	18.31	16.2	18.23
FF0251881	18.0	17.11	15.0	17.03
FF0245881	16.2	15.31	13.2	15.23
FF0239881	14.4	13.51	11.4	13.43
FF0235881	13.2	12.31	10.2	12.23
FF0233881	12.6	11.71	9.6	11.63
FF0229881	11.4	10.51	8.4	10.43
FF0227881	10.8	9.91	7.8	9.83
FF0225881	10.2	9.31	7.2	9.23
FF0221881	9.0	8.11	6.0	8.03
FF0215881	7.2	6.31	4.2	6.23



NOTE 1. REFER TO THE DRAWING SJ036196 FOR EVEN NUMBER OF CONTACTS.
NOTE 2. FPC COMPOSITION (RECOMMENDED) REFER TO TABLE 2
NOTE 3. LOT NUMBER IS MARKED ON THE TOP CENTER PORTION OF THE CONNECTOR.

注1. 偶数芯数のコネクタ寸法は SJ036196 参照。
注2. FPC構成 (推奨) TABLE 2 参照。
注3. ロット番号がコネクタ上面中央部に表記される。

DESIGNATION
命名法
FF02 * * SS 1

CONTACT FINISH
(1:GOLD OVER NICKEL(AU:0.1μm MIN))
コネクタめっき仕様 (1:ニッケル上金めっき(AU:0.1μm以上))

MODIFICATION S:NICKEL BARRIER
モディファイ ニッケルバリア

CONNECTOR FORM (S:SOCKET)
コネクタ形状 (S:ソケット)

NO. OF CONTACTS (N) (NOTE 1)
芯数 (N) (注1)

SERIES
シリーズ

TABLE 2

COMPOSITION 層名		THICKNESS (EXAMPLE) 厚さ (例)	NOTE 備考
GOLD PLATING 金めっき	ELECTROLYSIS PLATING 電解めっき	0.3~0.6 μm	0.1 μm MIN
NICKEL PLATING ニッケルめっき	ELECTROLYSIS PLATING 電解めっき	3~9 μm	SOFT TYPE IF AVAILABLE
COPPER 銅箔	ROLLED MATERIAL 圧延銅	18 μm	NOMINAL 18 μm MAX
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	13 μm	NONE (RECOMMENDED)
BASE FILM ベースフィルム	POLYIMIDE ポリイミド	25 μm	25 μm
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	15 μm	30 μm MAX
REINFORCE PLATE 補強板	POLYIMIDE ポリイミド	12.5 μm	-

4	ACTUATOR アクチュエータ	1	PPS		COLOR:BLACK/色相:黒 UL94V-0
3	BASE INSULATOR ベースインシュレータ	1	LCP		COLOR:WHITE/色相:白 UL94V-0
2	CONTACT 2 コネクタ 2	(N-1) 2	COPPER ALLOY 銅合金		PARTIAL GOLD OVER NICKEL(AU:0.1μm MIN.) 部分ニッケル上金めっき(AU:0.1μm 以上)
1	CONTACT 1 コネクタ 1	(N+1) 2	COPPER ALLOY 銅合金		PARTIAL GOLD OVER NICKEL (AUG:0.05μm MIN.) 部分ニッケル上金めっき (AUG:0.05μm 以上)
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
仕様書 (SPECIFICATION) JACS-1627 J AHL-1627		第1版 (ORIGINAL DATE) 1.Aug.2001	製図 DR.	シリーズ (SERIES) FF02	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
公差 (GENERAL TOLERANCE) 寸法 (DIMENSION) 角度 (ANGLES)		担当 CHK. 査閲 APPD. 承認 APPD.	K.INOUE O.HASHIGUCHI	名称 (TITLE) FF02 * * SS 1	図面番号 (DRAWING NO.) SJ036197
. ±0.8	×° ±			質量 (MASS)	版数 (REV.) 9
.X ±0.4	××° ±				
.XX ±0.1					
.XXX ±					

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